

# AN1425

## RF Amplifier for NXP Contactless NFC Reader ICs

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Application note  
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### Document information

Info	Content
<b>Keywords</b>	RFID, Antenna Design, RF Amplifier, Antenna Matching, contactless reader, NFC
<b>Abstract</b>	This application notes provides guidance on antenna and RF amplifier design for NXP contactless NFC reader devices, such as PN5xx and NXP contactless reader devices, such as MFRC52x.



## Revision history

Rev	Date	Description
2.4	20110802	<a href="#">Fig 1</a> updated
2.3	20110118	Power supply voltage limitation added in the general chapter
2.2	20081125	Minor changes on explanatory text
2.1	20081020	Filter at RX removed, Tuning impedance changed
1.0	20070801	Initial version

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## 1. Introduction

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### 1.1 General

Some of NXP contactless NFC reader IC's are designed for handheld devices and low power consumption which results in shorter read range performance. An RF amplifier can extend the usage of such devices to meet requirements for higher transmission performance and communication distance.

This application note is intended to give a practical guide to extend and optimize the transmission power performance and communication distance of NXP contactless NFC reader IC's. The document describes the design and dimension of antennas and RF amplifier circuits.

The amplifier circuit in this document is designed for a supply voltage of 5V (according to USB 2.0 specifications). For higher power supply voltages, the circuit as well as the components have to be accordingly adapted.

### 1.2 Reference documents

1. NFC specific datasheet
2. ISO/IEC 14443
3. ISO/IEC 18092: Near Field Communication – Interface and Protocol (NFCIP-1)

### 1.3 Reference Simulation Tools

1. RFSim99

## 2. How to use this document

The application note gives a practical guide to design antennas, calculate the matching components as well as implement an RF amplifier for NXP contactless NFC reader IC. It gives a guideline for complete RF circuit design, an introduction to the overall antenna design theory for RFID systems as well as a description of the transmitter matching resistance. Finally the matching procedure is described using a reference antenna which is connected to the amplifier circuit.

A guideline is given to design an antenna and the RF amplifier circuitry together with a tuning procedure. The guideline covers the following items:

2. RF field generation and data transmission
  - a. Fig 1 shows the recommended amplifier circuit with all relevant components required to connect an antenna to NXP's contactless NFC reader IC's. This circuit must not only ensure that energy and data can be transmitted to the target device but must also be designed to receive a target device's answer.
  - b. The antenna design part describes how to calculate the inductance of the antenna coil and gives basic hints on symmetry and environmental influences to be taken into consideration. The equivalent circuits and the relevant formulas are given as preparation for these calculations.
  - c. Formulas to calculate the amplifier and the matching circuit
  - d. Antenna tuning procedure
3. Receiver part
  - a. Design and calculation of the receiver circuit.
4. Examples on how to calculate the RF parts for a given antenna design and given contactless reader IC.

**Note:** This application note cannot and does not replace any of the relevant datasheets.

**Note:** The term "Card" used in this document refers to a contactless smart card according to the ISO14443 or a contactless smart card according to the FeliCa scheme.

**Note:** Design hints on how to place the components on a PCB are not included.

**Note:** All tuning and measurement of the antenna always has to be performed at the final mounting position to consider all parasitic effects like metal influence on quality factor, inductance and additional capacitance.

### 3. Block Diagram

The amplifier solution is designed to communicate in four different reader/writer operating modes:

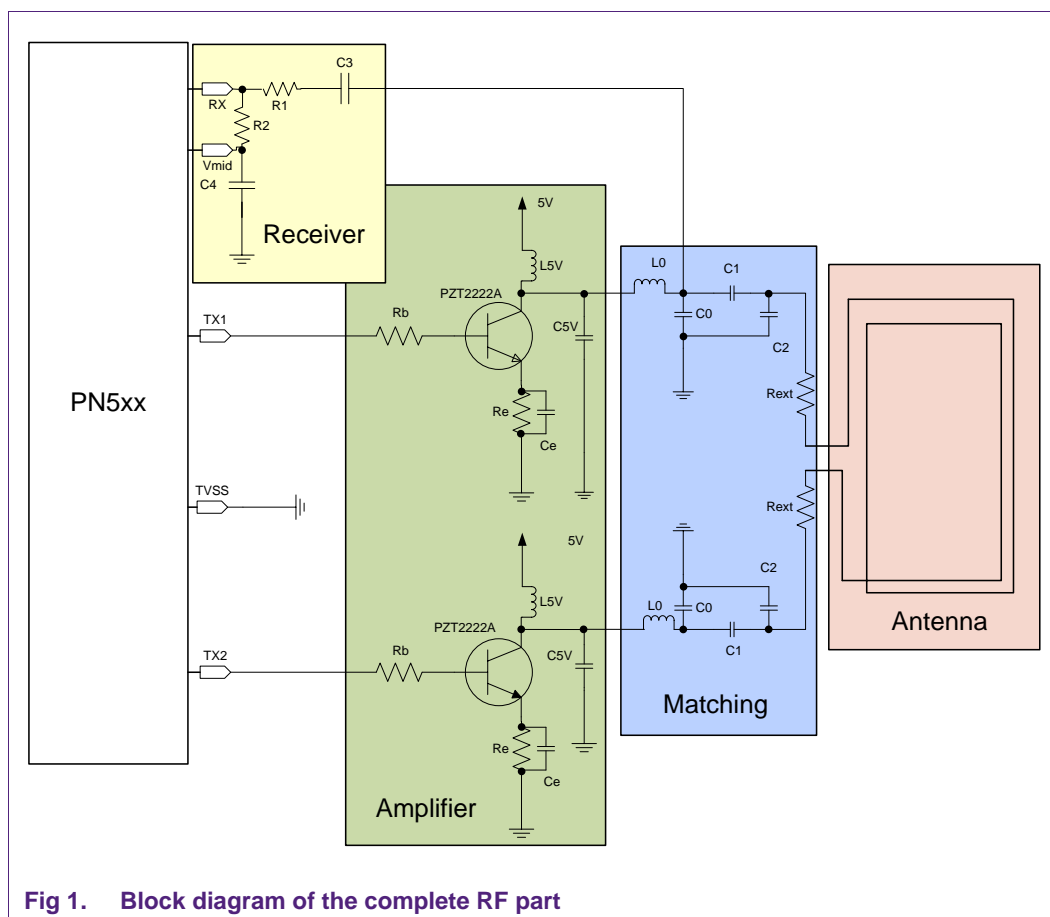
- Reader/Writer mode for communication with devices compliant to ISO/IEC14443A/B
- Reader/Writer mode for communication with devices compliant to MIFARE
- Reader/Writer mode for communication with devices compliant to FeliCa
- NFCIP-1 mode for communication to NFC devices

The following requirements have to be met by the amplifier circuit for NXP contactless reader:

- **Generate the RF field:** The generated magnetic field has to be maximized considering the limits of the transmitter supply current and general emission limits.
- **Transmit data:** The coded and modulated data signal has to be transmitted in a way, that every card and NFC device is able to receive it. The signal shape and timing has to be considered.
- **Receive data:** The response of a card or NFC device has to be transferred to the receive input of the PN5xx considering the datasheet limits like maximum voltage and receiver sensitivity.

The operating distance of NXP contactless NFC reader IC's depends on:

- matching of the antenna,
- sensitivity of the receiver,
- antenna size used in the reader system,
- antenna size of the communication partner and
- external parameters (e.g. metallic environment and noise).



**Note:** Fig 1 shows the RF part only. For proper operation, the analog and digital supplies plus the host interface also have to be connected to power supply.

Although some of these blocks may contain only a few passive components, it is important to consider all blocks and complete functionality to guarantee proper function of the complete device:

- The amplifier uses a transistor circuit to amplify the digital signal of the NXP contactless reader IC.
- The matching circuit acts as an impedance transformation block.
- The EMC filter as part of the matching circuit reduces the 13.56 MHz harmonics and performs an impedance transformation.
- The antenna coil itself generates the magnetic field.
- The receiver part provides the received signal to the NXP contactless reader internal receiver stage.

Basically, the complete RF circuitry consists of eleven capacitors, five inductors, eight resistors, two transistors and the symmetrical antenna coil.

**Note:** A center tap connection of the antenna may be neglected without negative influence on the EMC performance of the circuitry.

## 4. Description of Symmetric Amplifier

The colored boxes as well as the schematic in Fig 1 show the different parts of the circuit. Each box will be separately discussed in the following chapters.

### 4.1 Matching of the symmetric amplifier – Overview

#### 4.1.1 Amplifier Circuit

The Amplifier Circuit (TX-Path) (green box in Fig 1) consists of two emitter amplifiers where the transistors are used as a switch. The TX1 and the TX2 output of the NXP contactless reader chip generates a digital signal which is amplified by the transistors. The signal is directly connected to the matching circuit.

**Note:** The PN5xx has two transceiver pins: TX1 and TX2. By using the amplifier solution, the contactless reader transmission mode should be switched to *asynchronous mode*. This is done by setting the register 0x14 (TXControlReg) to 0x83.

The emitter amplifier consists of a resistor  $R_b$  which is connected to the base of the transistor. The resistor limits the current into the base. The collector of the transistor is connected via an AC – decoupling inductor (L5V) to the power supply. The quality factor of this inductor has to be at least more than 20 at 13.56MHz. At the same time the inductance L5V, in combination with C5V interacts as a 13.56 MHz oscillator. The resistor  $R_e$  and the capacitor  $C_e$  connect the emitter to GND. The matching circuit is connected to the collector of the transistor.

**Note:** It is possible to use any type of transistor which has a high transition frequency, a small collector capacitance and high total power dissipation. The concrete values of these three factors depend on the requirements of the application

#### 4.1.2 Antenna Matching

Depending on the antenna PCB (red box in Fig 1), the necessary antenna matching (blue box Fig 1) consists of a symmetric arrangement of an EMC – filter (L0 and C0) plus a serial and parallel tuning capacitors, from the reader chip point of view. To regulate the quality factor of the antenna, the resistor  $R_q$  is added.

The capacitors and the resistors are used to both achieve the required 13.56MHz resonance frequency, and a quality factor for appropriately signal shaping according to ISO/IEC 14443.

The following equations in chapter 4.1.3 are used to calculate the matching components. Please keep in mind, that these values, slightly modified, are also required for fine tuning the components. This is necessary because of the direct influence of the amplifier circuit onto the phase shifting of the two signals on both sides of the antenna matching circuit. The maximum output is reached when the antenna is first tuned to 13.56MHz and the two ends of the antenna tuning circuit, connected to the amplifier, oscillate (in relation to GND) with 180 degree phase shift.

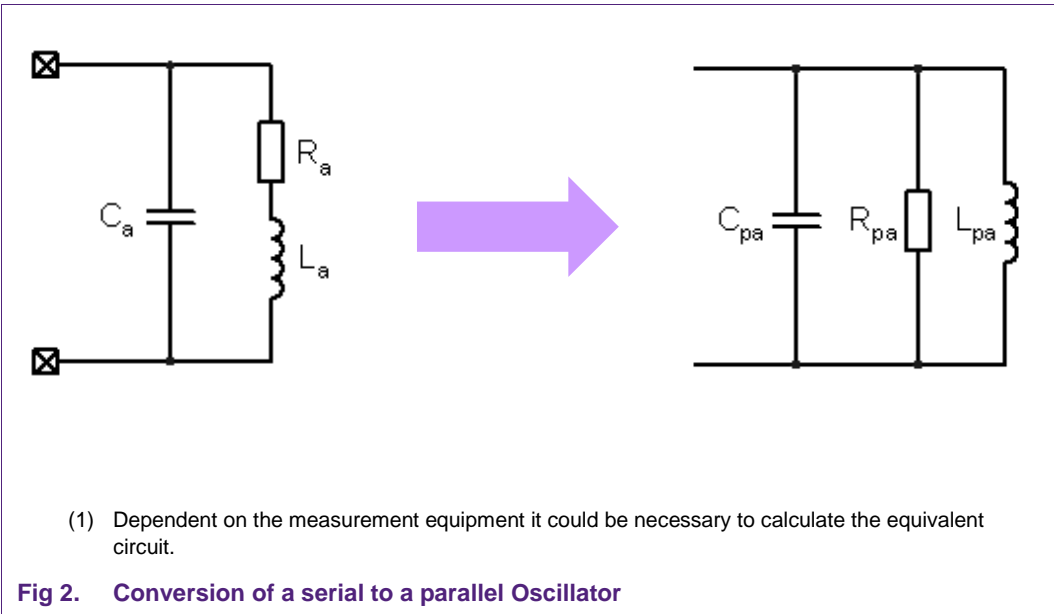
The electrical parameters of the antenna  $L_p$ ,  $R_p$  and  $C_p$  have to be measured first.

**Note:** The matching of the antenna is very strong influenced by its environment. An assembled PCB or other metallic environment, like a display or housing will make a retuning necessary.

4.1.3 Mathematical Deduction

4.1.3.1 Calculation of the Equivalent circuit with the focus on the quality factor

Measuring the antenna by using a network analyzer or a RFA-Bridge, gives the inductance ( $L_a$ ), the serial resistor ( $R_a$ ), as well as the natural frequency ( $f_{nat}$ ). To calculate the tuning capacitors, the components for the equivalent parallel circuit have to be calculated first.



The adjustment of the quality factor for the antenna has to be done during the calculation of the equivalent circuit. This is done by additional ohmic resistors, which changes the  $R_{sges}$ . (Refer to Table 1 and chapter 6)

Table 1. Mathematical deduction to calculate the equivalent circuit

Step	Equation	Comment
1. Calculation of the $R_{sges}$	$Q = \frac{\omega L_{pa}}{R_{sges}}$	$L_{pa}$ ....Measured $\omega$ for 13.56MHz Q...chosen



Step	Equation	Comment
2. Out of $R_{sges}$ one can calculate $R_{pa}$	$R_{pa} = \frac{(\omega L_{pa})^2}{R_{sges}}$	$L_{pa}$ ...done $R_{pa}$ ...done
3. Calculation of $C_{pa}$	$f_{nat} = \frac{1}{2\pi\sqrt{(L_{pa} \cdot C_{pa})}}$	$f_{nat}$ ... Mearsured $L_{pa}$ ....Measured $C_{pa}$ ...done

4.1.3.2 Calculation of the tuning capacitors

Due to the filter structure, it is necessary to split the circuit to calculate the tuning capacitors.  $R_{match} = Z_{match} \leq 180 \text{ Ohm}$

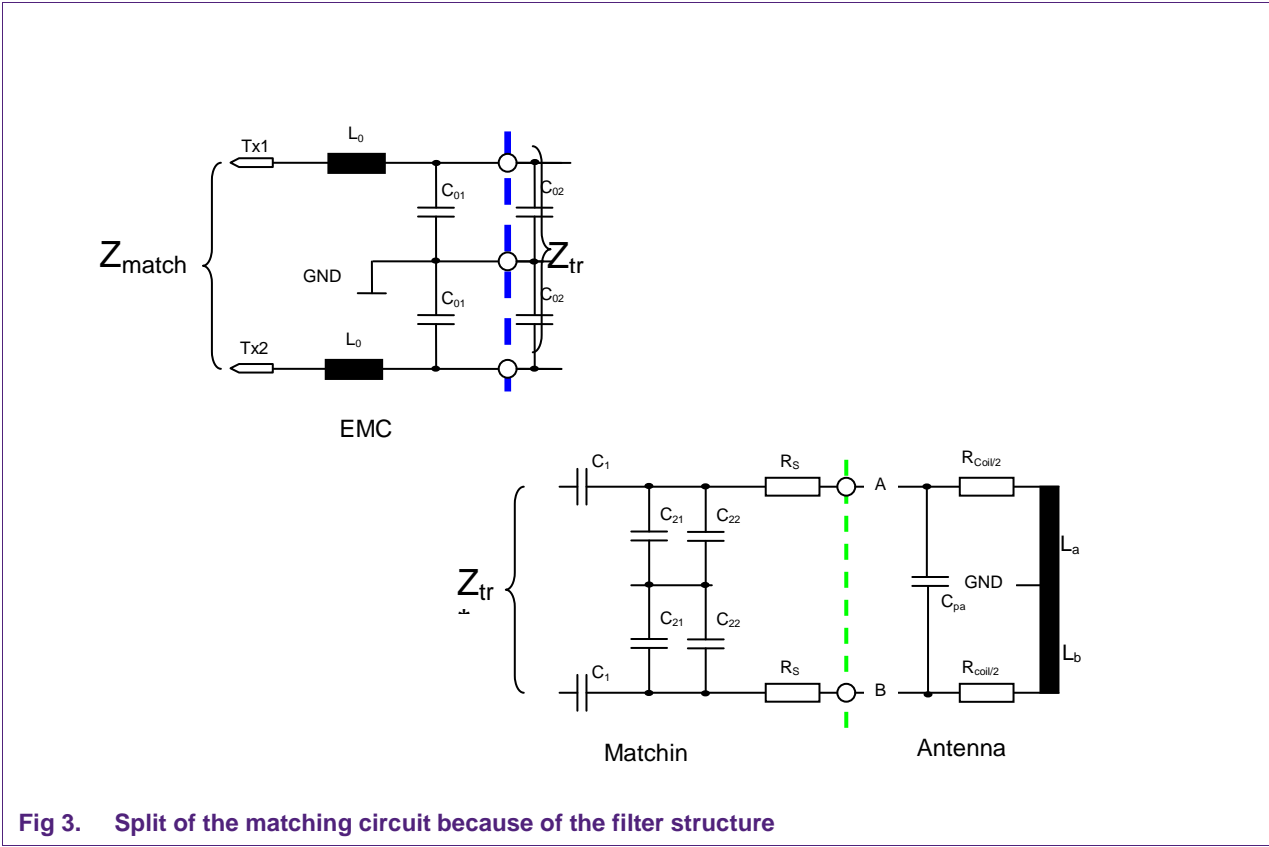


Fig 3. Split of the matching circuit because of the filter structure

$$Z_{tr} = R_{tr} + jX_{tr}$$

$$R_{tr} = \frac{R_{match}}{\left(1 - \omega^2 \cdot L_0 \cdot C_0\right)^2 + \left(\omega \cdot \frac{R_{match}}{2} \cdot C_0\right)^2}$$

$$X_{tr} = 2 \cdot \omega \cdot \frac{L_0 \cdot \left(1 - \omega^2 \cdot L_0 \cdot C_0\right) - \frac{R_{match}^2}{4} \cdot C_0}{\left(1 - \omega^2 \cdot L_0 \cdot C_0\right)^2 + \left(\omega \cdot \frac{R_{match}}{2} \cdot C_0\right)^2}$$

**Fig 4. Equations to calculate the tuning capacitors (part 1)**

The split of the matching circuit allows calculating the matching capacities with following equations.

$$C_1 \approx \frac{1}{\omega \cdot \left( \sqrt{\frac{R_{tr} \cdot R_{pa}}{4}} + \frac{X_{tr}}{2} \right)}$$

$$C_2 \approx \frac{1}{\omega^2 \cdot \frac{L_{pa}}{2}} - \frac{1}{\omega \cdot \sqrt{\frac{R_{tr} \cdot R_{pa}}{4}}} - 2 \cdot C_{pa}$$

Fig 5. Equations for the calculation of the tuning capacitors (part 2)

**Note:** For calculating the tuning capacities NXP provides an Excel sheet [1] where all this calculations are done automatically.

#### 4.1.4 Receive Path

The receiver path (yellow box at Fig 1) consists of a voltage divider and two capacitors. The capacitor  $C_3$  is necessary to decouple DC voltage and the following resistor  $R_3$  limits the voltage to prevent clipping at the  $R_x$  – pin of the NXP contactless reader IC.

To guarantee a well tuned receiver circuit, one needs to consider both: the voltage level and also the receive threshold. Refer also to the data sheet of the contactless reader IC.

## 5. Antenna Design

### 5.1 Antenna Inductance

The following two sections show the formulae to estimate the antenna inductance in free air.

To estimate antenna values under influence of metal (such as shielding planes or batteries in devices) simulation software is required which can calculate the antennas parameters in these environments.

#### 5.1.1 Circular Antennas

The inductance can be estimated by the following formula (see also Fig 6):

$$L_a [nH] = \frac{24.6 \cdot N_a^2 \cdot D [cm]}{1 + 2.75 \cdot \frac{s [cm]}{D [cm]}} \quad (1)$$

D Average antenna diameter

s Antenna width

N<sub>a</sub> Number of turns

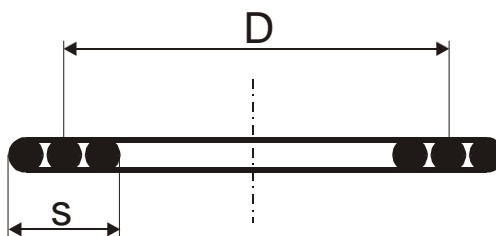


Fig 6. Circular Antenna

#### 5.1.2 Rectangular Antennas

The inductance can be calculated by following formula (see also Fig 7):

$$L_a = \frac{\mu_0}{\pi} \cdot [x_1 + x_2 - x_3 + x_4] \cdot N_a^{1.8} \quad (2)$$

Table 2. Calculations for rectangular antenna

With:

$$d = \frac{2 \cdot (t + w)}{\pi}$$

$$a_{avg} = a_o - N_a \cdot (g + w) \qquad b_{avg} = b_o - N_a \cdot (g + w)$$

$$x_1 = a_{avg} \cdot \ln \left[ \frac{2 \cdot a_{avg} \cdot b_{avg}}{d \cdot \left( a_{avg} + \sqrt{a_{avg}^2 + b_{avg}^2} \right)} \right] \qquad x_2 = b_{avg} \cdot \ln \left[ \frac{2 \cdot a_{avg} \cdot b_{avg}}{d \cdot \left( b_{avg} + \sqrt{a_{avg}^2 + b_{avg}^2} \right)} \right]$$

$$x_3 = 2 \cdot \left[ a_{avg} + b_{avg} - \sqrt{a_{avg}^2 + b_{avg}^2} \right] \qquad x_4 = \frac{a_{avg} + b_{avg}}{4}$$

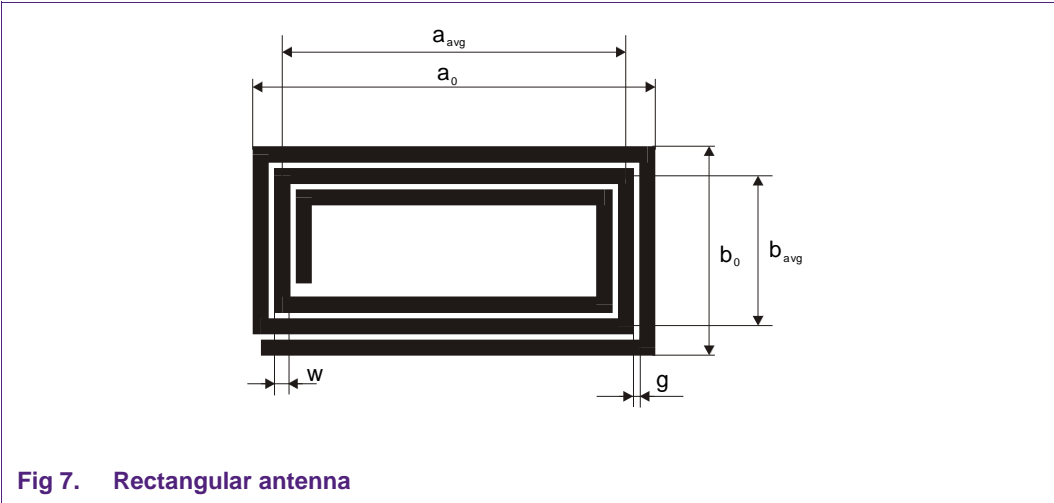


Fig 7. Rectangular antenna

- Variables:
- $a_o, b_o$  Overall dimensions of the coil
  - $a_{avg}, b_{avg}$  Average dimensions of the coil
  - $t$  Track thickness
  - $w$  Track width
  - $g$  Gap between tracks
  - $N_a$  Number of turns
  - $d$  Equivalent diameter of the track

## 5.2 Number of Turns

Depending on the antenna size, the number of turns should be chosen in a way to achieve an antenna inductance between 300 nH and 3  $\mu$ H.

The parasitic capacitance should be kept as low to achieve a self-resonance frequency > 35 MHz.

For many applications and antenna sizes, the number of turns will be in the range  **$N_a = 1 - 6$** .

A low number of turns is preferred to minimize the effects of coupling between antennas. The lower the numbers of turns are used, the smaller will be the influence of coupled devices such as a card or a 2<sup>nd</sup> NFC device in "Card Mode". It is especially important to minimize the detuning effect on the 1<sup>st</sup> device in very close proximity between the antennas where this coupling has maximum impact. The overall performance loss due to low number of turns is negligible.

## 5.3 Antenna Quality Factor

The quality factor reflects the stored energy in the antenna. When the Q – factor is high the antenna needs more time to react on modulation, but radiates more energy. This directly influences the shaping of the radiated and modulated signal and the operating volume.

The bandwidth B –pulse width multiplied by T is defined as:

$$B \cdot T \geq 1 \quad (3)$$

With the bandwidth definition

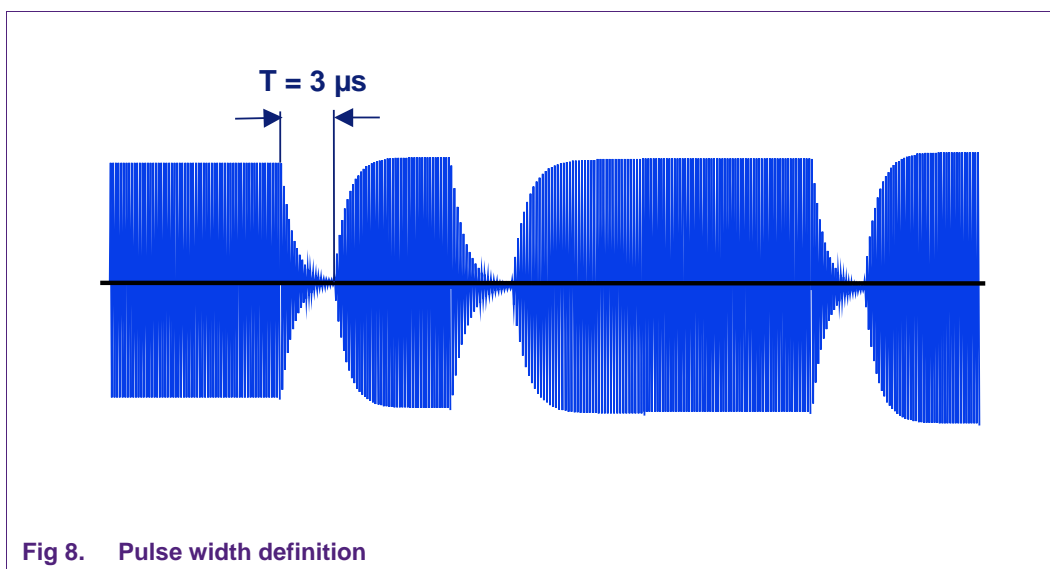
$$B = \frac{f}{Q} \quad (4)$$

B multiplied by T results into

$$Q \leq f \cdot T$$

$$Q \leq 13.56 \text{ MHz} \cdot 3 \mu\text{s}$$

$$Q \leq 40.68$$



The recommended antenna quality factor to be used is defined to be  $Q_a \leq 30$ .

## 6. Implementation Guideline

This chapter explains a step by step process to design and tune the amplifier circuit.

### 6.1 Antenna and tuning circuit

The example uses an antenna PCB with the size of 84 mm x 64 mm and 2 turns.

#### 6.1.1 Measurement of the Antenna

Measure the inductance  $L_{pa}$ , the serial resistance  $R_s$  and the self-resonance frequency  $f_{nat}$  of the antenna with a network analyzer or equivalent equipment.

The example antenna has following values:

**Table 3. Measured Values of Sample Antenna**

Antenna	Value
$L_{pa}$	811nH
$R_{sAntenna}$	370mΩ
$f_{nat}$ (of the Antenna)	89.7MHz

#### 6.1.2 Calculation of the Resistance of the Equivalent Circuit

Calculation of the additional resistor  $R_{ext}$ , for a quality factor of 25 (refer to Table 1: Mathematical deduction to calculate the equivalent circuit).

A quality factor of 25 was chosen to guarantee the needed shaping for the modulation.

$$R_{sges} = \frac{\omega L_{pa}}{Q} = \frac{2 * \pi * 13.56MHz * 811nH}{25} = 2.76Ohm$$

$$R_{ext} = \frac{R_{sges} - R_{sAntenna}}{2} = \frac{2.76Ohm - 0.37Ohm}{2} = 1.2Ohm$$

**Table 4. Description of the ohmic resistors for the sample antenna**

Name	Description
$R_{sAntenna}$	Ohmic resistance of the Antenna; measured
$R_{ext}$	Additional calculated resistors needed to reach the quality factor Q of 25
$R_{sges}$	Complete resistance consist of the $R_{sAntenna} + 2 * R_{ext}$



### 6.1.3 Calculate out of $R_{sges}$ the equivalent $R_{pa}$

$$R_{pa} = \frac{(\omega L_{pa})^2}{R_{sges}} = \frac{(2 * \pi * 13.56 MHz * 811 nH)^2}{2.76 Ohm} = 1.73 kOhm$$

### 6.1.4 Calculation of the Parallel Capacity of the Antenna.

$$C_{pa} = \frac{1}{\omega_{nat}^2 L_{pa}} = \frac{1}{(2 * \pi * 89.7 MHz)^2 * 811 nH} = 3.88 pF$$

**Note:** The capacitance is a behavior of the antenna and is calculated using the measured inductance and “natural frequency” of the antenna.

### 6.1.5 Calculation of the tuning Capacitances

$$C1 = \frac{1}{\omega \cdot \sqrt{\frac{R_{tr} \cdot R_{pa}}{4} + \frac{X_{tr}}{2}}} \approx 68 pF$$

$$C2 = \frac{1}{\omega^2 \cdot \frac{L_{pa}}{2}} - \frac{1}{\omega \sqrt{\frac{R_{tr} \cdot R_{pa}}{4}}} - 2 \cdot C_{pa} \approx 280 pF$$

**Note:** NXP provides an Excel sheet [1] to calculate the tuning capacitors

#### 6.1.5.1 Simulation

The simulation shows the arrangement of the matching circuit plus its smith chart

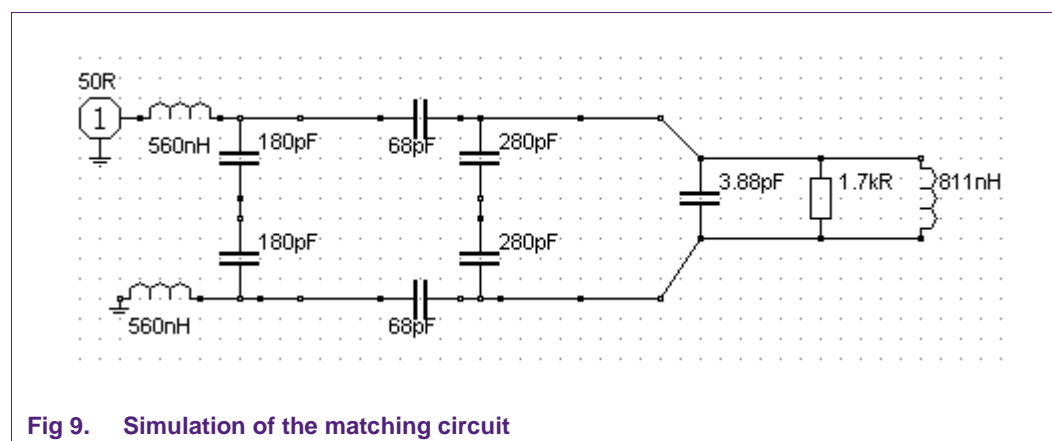
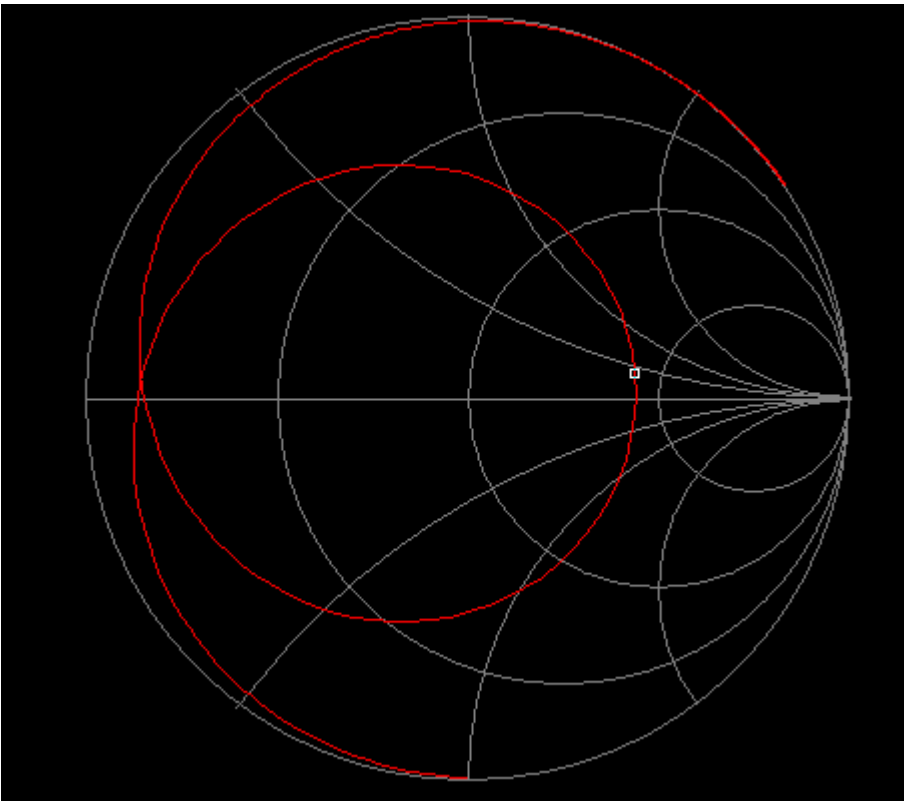


Fig 9. Simulation of the matching circuit



(1) Smith chart 10MHz to 30 MHz; Marker Z= 124,5 Ohm at 13.56MHz

Fig 10. Smith chart of the simulation

Table 5. Values of the Tuning Circuit

Component	Value
$R_{ext}$	1.2Ohm
C1	68pF
C2	280pF
C0	180pF
L0	560nH

6.2 Amplifier Circuit

The amplifier circuit (refer to Fig 11) consists of a symmetric arrangement of emitter amplifiers followed by a filter. The resistor  $R_b$  at the transistor base controls the input current. The components  $C_e$  and  $R_e$  in the emitter path of the transistor stabilize the biasing of the transistor.  $R_e$  limits the current and  $C_e$  acts in combination with  $R_b$  as a low pass. The antenna is connected to the collector and AC- decoupled connected to the power supply.

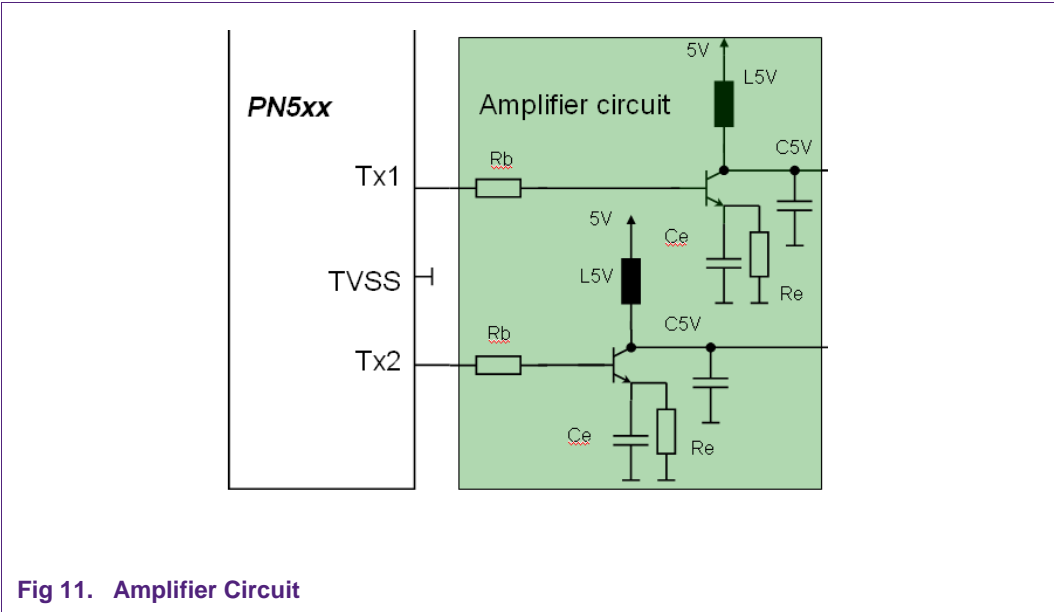


Fig 11. Amplifier Circuit

The main element of the amplifier is a symmetric arrangement of emitter amplifier. The  $L_{5V}$  decouples the AC-signal from the DC- supply. It also acts in combination with  $C_{5V}$  as a 13.56MHz oscillator to filter the digital signal coming from TX of the NXP contactless reader IC. To keep this decoupling as stable as possible, a quality factor of  $Q < 30$  is recommended. The antenna is connected to the collectors of the transistors.

Table 6. Component Values of the Receive Path

Components for receive filter	Values
$R_b$	220hm
$C_e$	22pF
$R_e$	180hm
$L_{5V}$	1,5uH, $Q \geq 20$ @ 13.56MHz
$C_{5V}$	91pF
$T_1, T_2$	PZT2222A

6.3 Receive Path

C<sub>3</sub> decouples the DC-voltage. The resistors R<sub>1</sub> and R<sub>2</sub> limit the voltage to prevent clipping at the Rx – pin of the NXP contactless reader IC.

**Note:** The voltage at R<sub>x</sub> should never be higher than 3 Vpp (measured with a low capacitance probe). Increase the resistor R<sub>1</sub> if the voltage is too high.

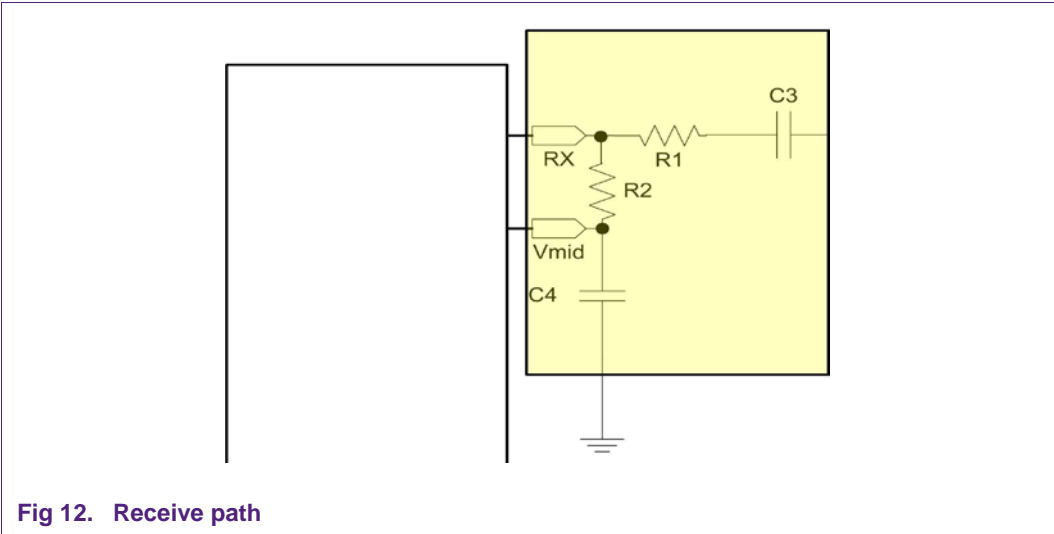


Table 7. Component Values of the Receive Path

Components for receive filter	Values
R <sub>1</sub>	3.3kOhm
R <sub>2</sub>	1kOhm
C <sub>3</sub>	1nF
C <sub>4</sub>	100nF

## 6.4 Summary

### 6.4.1 Component list

Following Table 8 shows the component values of the complete amplifier circuit by using the antenna parameters found in 6.1.1.

**Table 8. Values of the amplifier circuit**

Components	Values
$C_0$	180pF
$C_1$	68pF
$C_2$	280pF
$C_3$	1nF
$C_4$	100nF
$C_{5V}$	91pF
$C_e$	22pF
$L_0$	560nH
$L_{5V}$	1.5uH, $Q \geq 20$ @ 13.56MHz
$R_1$	3.3kR
$R_2$	1kR
$R_b$	22R
$R_e$	18R
$T_1, T_2$	PZT2222A

## 7. Fine Tuning

A well matched antenna can be achieved by fine tuning the circuit. The adjustments needed to be done are based on the receiving and matching block.

- The resistor  $R_1$  in the receiving path, in combination with  $R_2$ , is a voltage divider which regulates the voltage level at the  $R_X$  pin. The voltage level should not exceed 3 Vpp, but should be maximized for optimum R/W performance. The measurement of the voltage level at the  $R_X$  pin needs to be done with a low capacitance probe. Furthermore, those measurements needs to be done in the final housing/position as well as with different loads (targets) which detune the antenna and affects the RX signaling.
- In order to optimize the antenna tuning bring the antenna into its final housing/position and tune the antenna by changing  $C_1$ ,  $C_2$  and  $C_0$ . The optimum matching impedance for the antenna differ from design to design, but should be in the range between  $Z=100 \pm j0$  (@13.56 MHz) and  $Z=180 \pm j0$  (@13.56 MHz). A good starting point would be at  $Z=150 \pm j0$  (@13.56 MHz).

## 8. References

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- [1] AN166510 – Amplifier antenna matching calculation

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